














PREPARATION METHOD

PRINTED CIRCUIT BOARD (NON ASSEMBLED)

 CUTTING		Equipment QATM Qcut / Brillant	Consumable Cut-off wheel: corundum, resin bond Anti-corrosion coolant				
 MOUNTING		Equipment Pressure unit	Consumable KEM 20			Method Cold mounting	
 GRINDING/ POLISHING		Equipment QATM Qpol / Saphir Sample size \varnothing 40 mm					
STEP	MEDIUM		 rpm		 N	 min	
 Planar grinding	SiC-paper/foil P180 (180)	H ₂ O	250-300	▶▶ Synchronous rotation	30	Until plane (slightly before point of interest)	
 Grinding	SiC-paper/foil P800 (500)	H ₂ O	250-300	▶▶ Synchronous rotation	25	1:00 (until point of interest)	
 Grinding	SiC-paper/foil P1200 (600)	H ₂ O	250-300	▶▶ Synchronous rotation	25	1:00 (until point of interest)	
 Polishing	GAMMA/DELTA	Dia Complete Poly, 3 μ m	120-150	▶▶ Synchronous rotation	30	3:00	
 Final polishing	OMEGA	Eposal, 0.06 μ m	120-150	◀▶ Counter rotation	25	2:00 (H ₂ O during final 0:30)	